

L2F6 thru L2F7

Surface Mount Glass Passivated Fast Recovery Rectifier
 Reverse Voltage 800 -1000V Forward Current 2A

Features

- Glass passivated fast recovery rectifiers
- Ideal for automated placement
- Low forward voltage drop
- Low leakage current
- Moisture sensitivity level:1 Per J-STD-020
- Solder dip 260°C, 10s
- Low profile



Package: eSGB (SMAF)



RoHS
COMPLIANT

Maximum Ratings (T_A = 25°C unless otherwise noted)

Parameter	Symbol	L2F6	L2F7	Unit
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	800	1000	V
Maximum RMS Voltage	V _{RMS}	560	700	V
Maximum DC Blocking Voltage	V _{DC}	800	1000	V
Maximum Average Forward Rectified Current	I _{F(AV)}	1.0		A
Peak Forward Surge Current (8.3 ms Single Half Sine-Wave Superimposed on Rated Load)	I _{FSM}	50		A
Operating Junction, Storage Temperature Range	T _J , T _{STG}	- 55 to + 150		°C

Electrical Characteristics (T_A = 25°C unless otherwise noted)

Parameter	Test Conditions	Symbol	L2F6	L2F7	Unit
Maximum Instantaneous Forward Voltage	I _F =2A, T _J =25°C	V _F	1.3		Volts
Maximum DC Reverse Current at Rated DC Blocking Voltage	T _A =25°C	I _R	5.0		μA
	T _A =125°C		50		
Typical Reverse Recovery Time	I _F =0.5A, I _R =1.0A, I _{rr} =0.25A	t _{rr}	500		nS
Typical Junction Capacitance	4.0 V, 1 MHz	C _J	11		pF
Typical Thermal Resistance	junction to mount	R _{θJM} ¹⁾	12		°C/W

Note1: Thermal resistance from junction to mount, mounted on PCB with 8.0×8.0mm copper pads

Ratings and Characteristics Curves

($T_A = 25^\circ\text{C}$ unless otherwise noted)

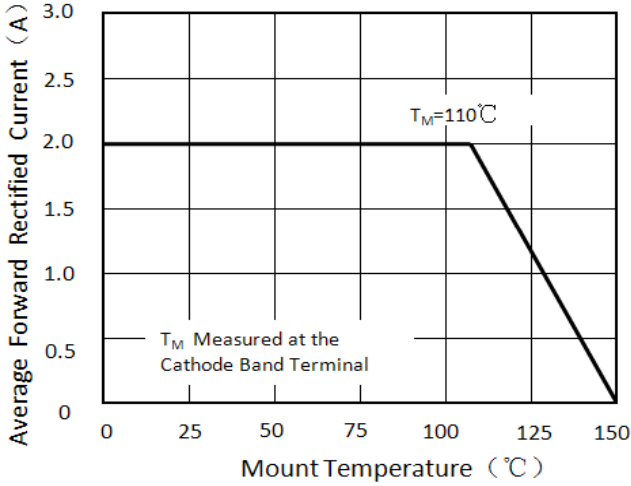


Figure 1. Forward Current Derating Curve

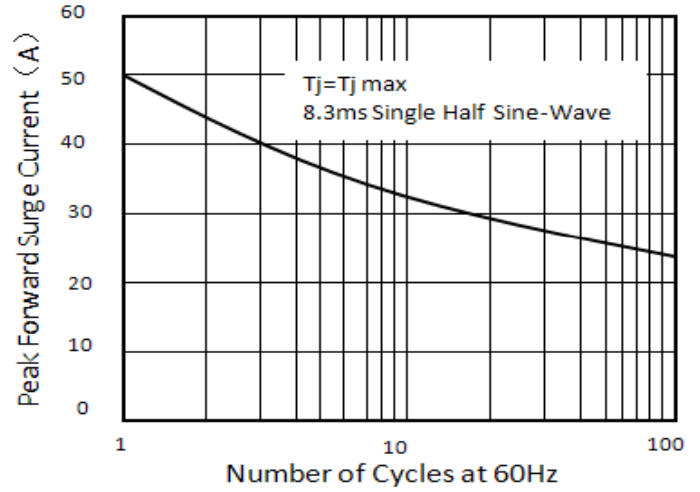


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

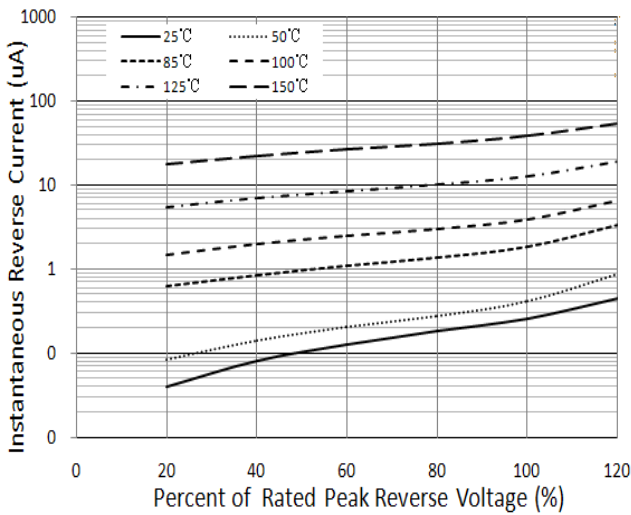


Figure 3. Typical Reverse Characteristics

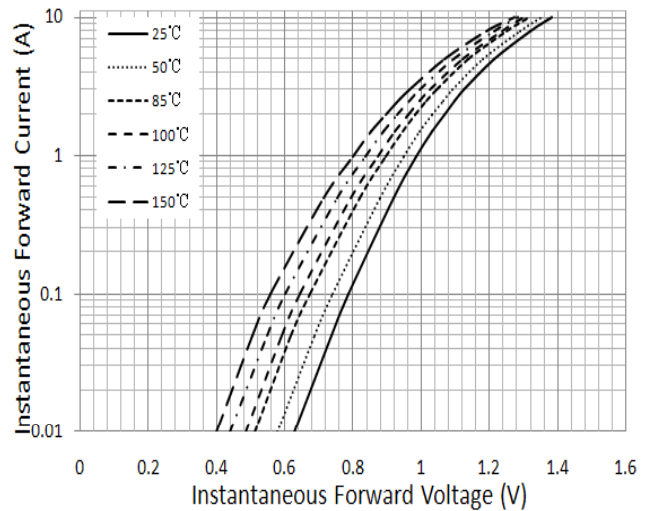


Figure 4. Typical Instantaneous Forward Characteristics

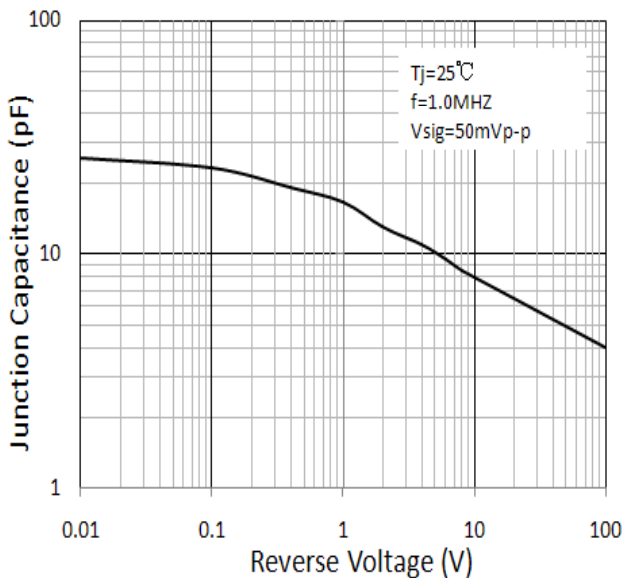


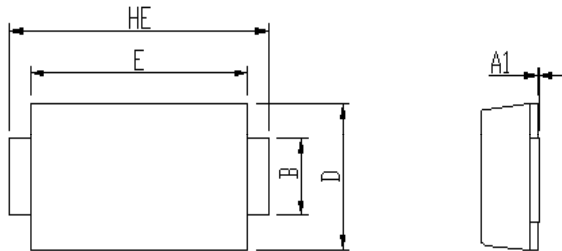
Figure 5. Typical Junction Capacitance

L2F6 thru L2F7

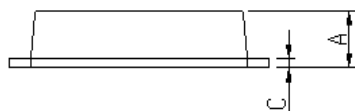
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Package Outline Dimensions

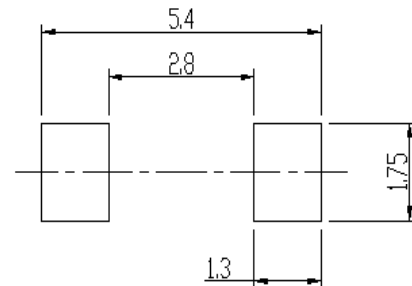
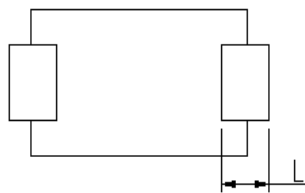
Package: eSGB (SMAF)



DIM	Unit: mm		Unit: inch	
	MIN	MAX	MIN	MAX
A	0.92	1.08	0.036	0.043
A1	0	0.1	0.000	0.004
B	1.25	1.45	0.049	0.057
C	0.1	0.25	0.004	0.010
D	2.6	2.8	0.102	0.110
E	4.1	4.3	0.161	0.169
L	0.7	1.1	0.028	0.043
HE	4.8	5.2	0.189	0.205



Soldering footprint



Packing Information

Packing quantities:

3000 pcs/Reel, 12mm Tape, 13" Reel

Tape & Reel Specification

